

**IEEE SW Test Workshop**  
Semiconductor Wafer Test Workshop

**Roger Hayward**  
Cascade Microtech



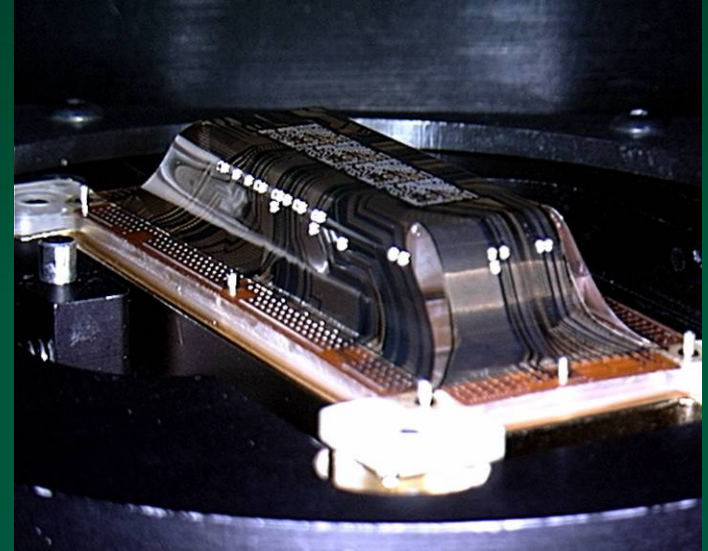
# Overcoming the Challenges of Parallel RF Test



**June 8-11, 2008**  
**San Diego, CA USA**

# Outline

- The Challenges
- Roadblocks
- Clearing the Obstacles
- Summary



# The Challenges

## *Decrease the cost to wafer-test RF devices*

- Cost to Test one die:

$$\text{Cost/die} = f\left(\frac{\$_{\text{ProbeCard}}}{\text{Touchdowns}} + \$_{\text{Station}} * t_{\text{Test}}\right)$$

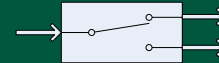
- From this:
  - Increase Life of Probe card (more touchdowns).
  - Minimize Test Time.
  - Test more die per touchdown.
- Setup:
  - You have “zero time” to debug the test program, after wafers arrive.
- It's all easy, right?



# The Challenges

## *Example: SPDT RF Switch*

- Known Good Die RF Test:
  - Confirm Operation.
  - Verify:
    - Low Insertion Loss (connected path)
    - Isolation (disconnected path)
    - Linearity (3<sup>rd</sup> Harmonic)



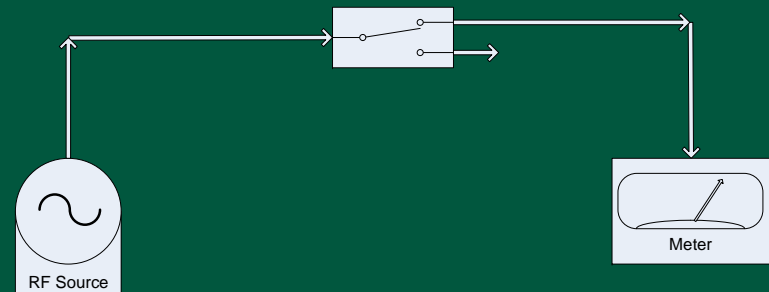
- Consider testing in parallel:
  - 1 die

# The Challenges

## *Example: SPDT RF Switch*

- Known Good Die RF Test:
  - Confirm Operation.
  - Verify:
    - Low Insertion Loss (connected path)
    - Isolation (disconnected path)
    - Linearity (3<sup>rd</sup> Harmonic)

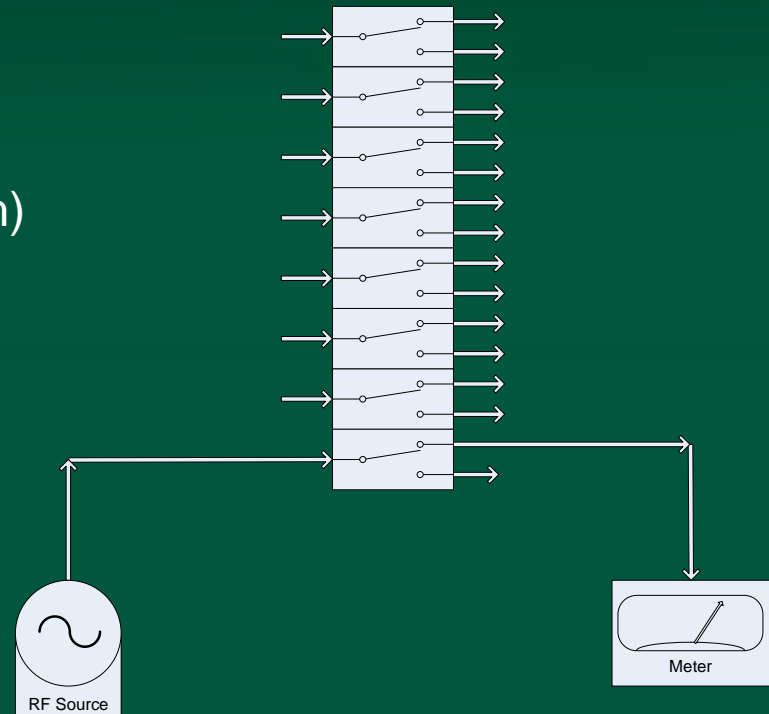
- Consider testing in parallel:
  - 1 die



# The Challenges

## Example: SPDT RF Switch

- Known Good Die RF Test:
  - Confirm Operation.
  - Verify:
    - Low Insertion Loss (connected path)
    - Isolation (disconnected path)
    - Linearity (3<sup>rd</sup> Harmonic)
- Consider testing in parallel:
  - 1 die
  - 2 die
  - 8 die?



# Roadblocks

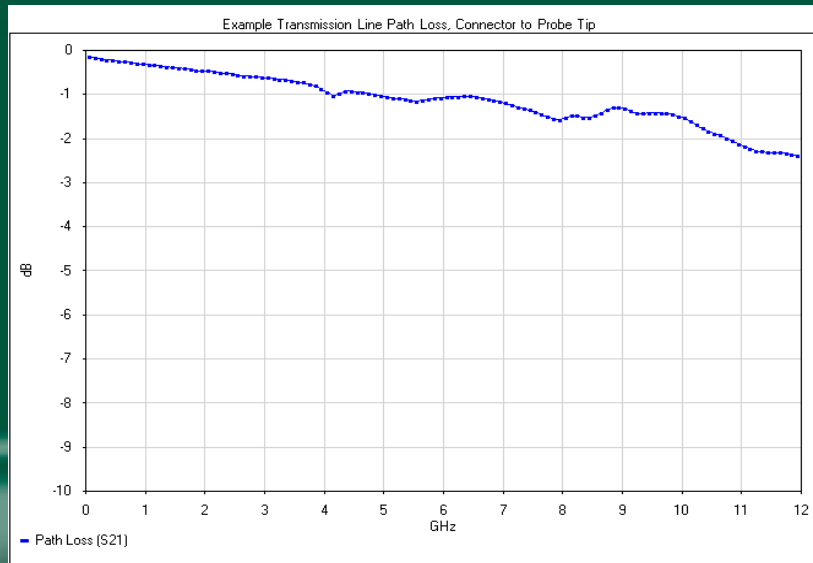
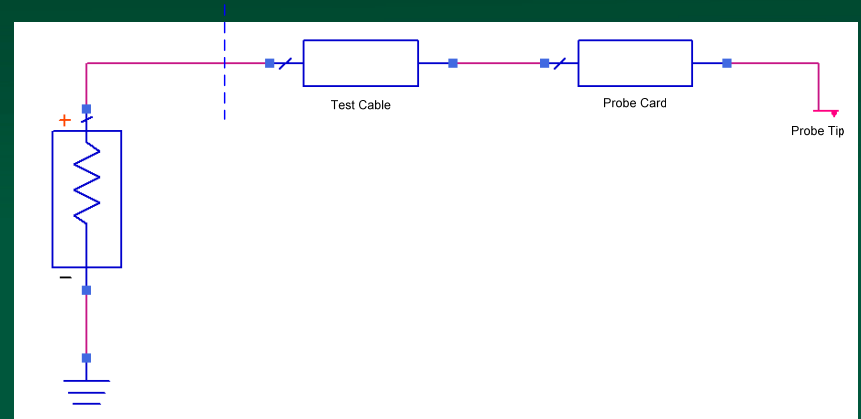
- RF Calibration
- RF Isolation
- Parallelism
- Multi-DUT Test Program Debug
- Wafer and Prober Availability



# Roadblock #1

*Do you know the losses of your transmission path?*

- RF Calibration



- All probes have path loss
  - (Some have less than others).
- Characterize the loss
- Subtract from measurement

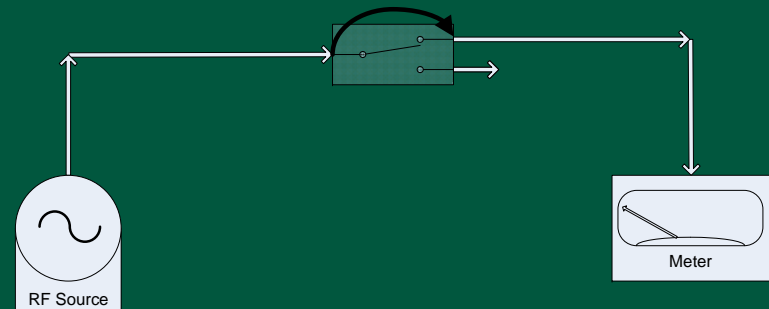
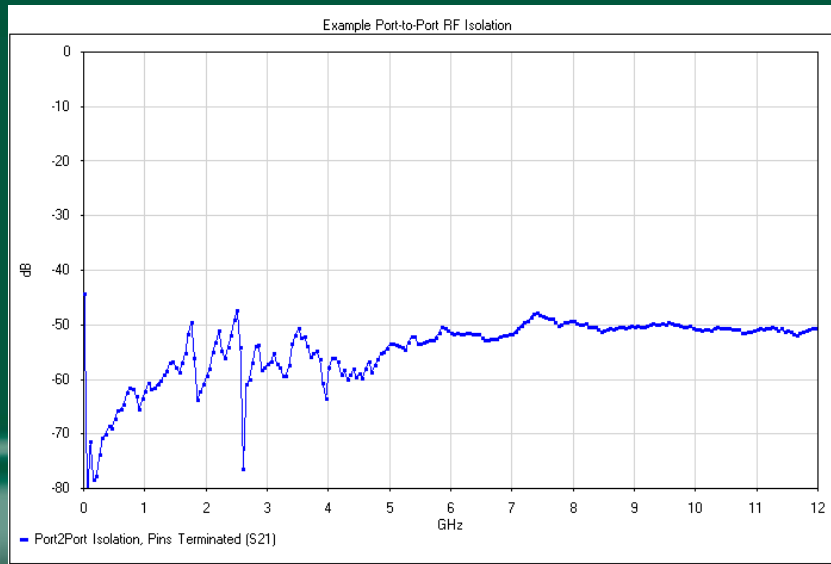




# Roadblock #2

*Are you measuring your die or your probe card?*

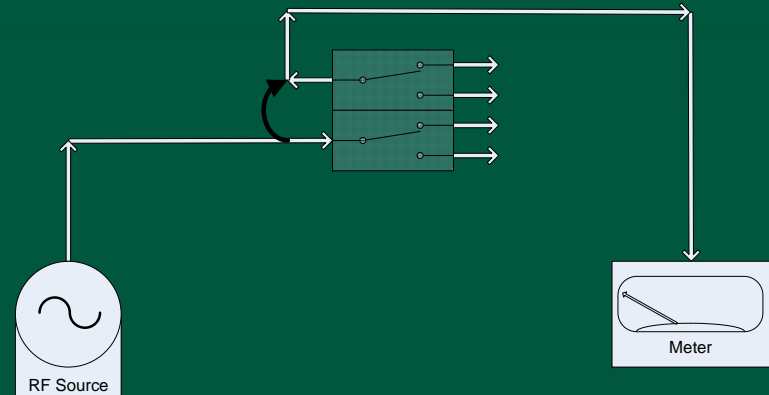
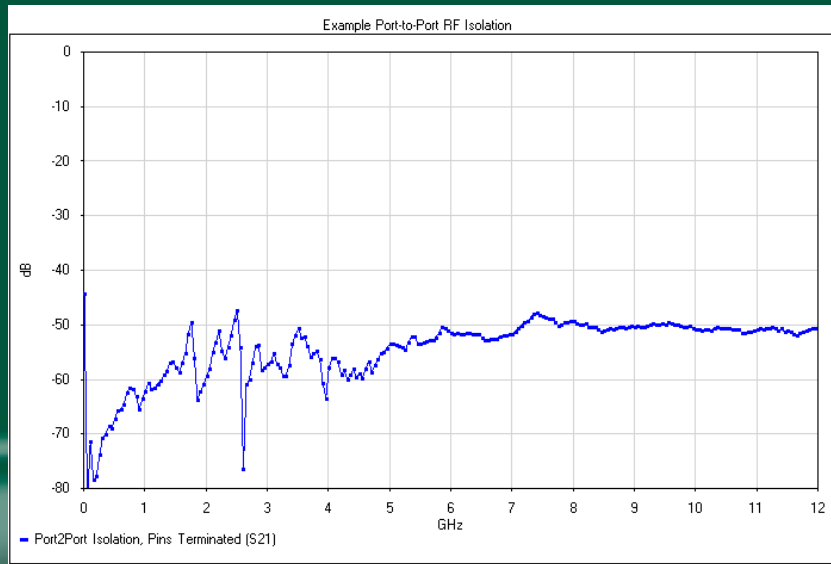
- RF Isolation
  - Port-to-Port
  - Die-to-Die



# Roadblock #2

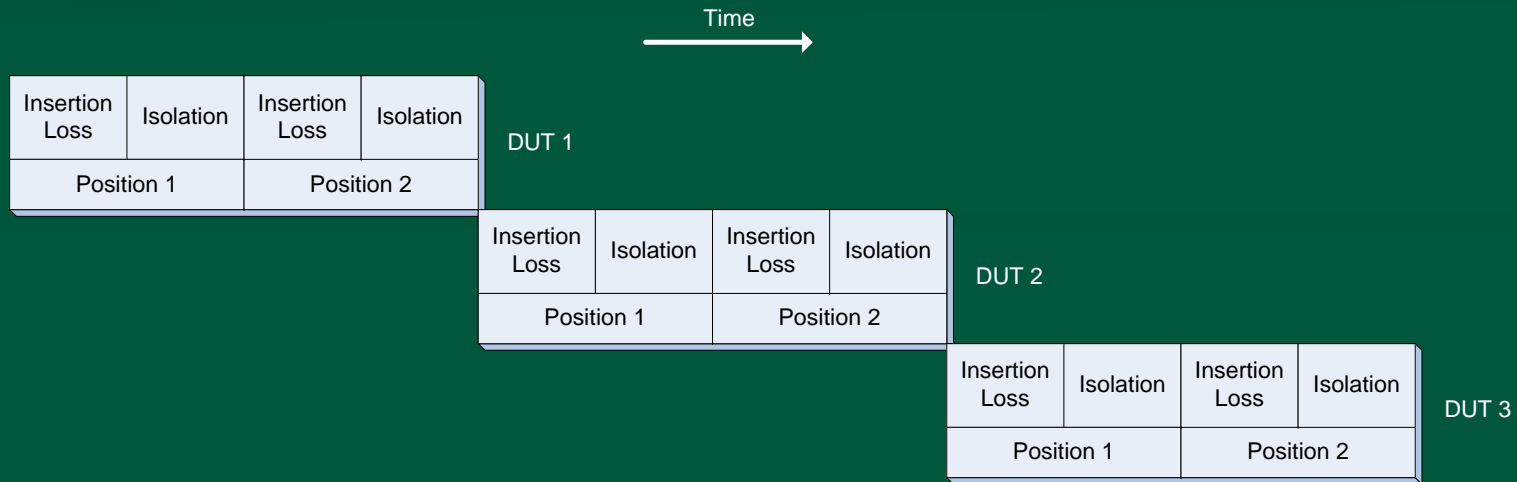
*Are you measuring your die or your probe card?*

- RF Isolation
  - Port-to-Port
  - Die-to-Die



# Roadblock #3

*Have you fully-optimized your test program?*



# Roadblock #4

*Have you fully debugged your probe card?*

- *How much time do you have to optimize this program?*
- *How many wafers will you get to use?*
- *What is broken:*
  - *The silicon?*
  - *The test program?*
  - *The probe card?*



# Clearing the Obstacles

## *Building your system*

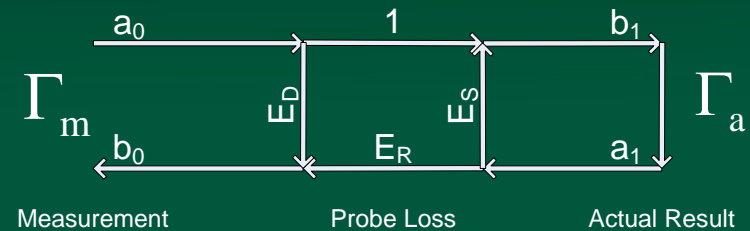
- RF Calibration:
  - Vector
  - Scalar
    - Direct measurement
    - Short-Open
- Catering your system for Parallel Test
- Test Optimization



# RF Calibration

## What is it?

- Probes have electrical loss.
- Measurements include the loss.
- *Calibration:*
  - Characterize the transmission path.
  - Remove (de-embed) the loss from the measurements.
- *Scalar Calibration:*
  - Magnitude loss only.
- *Vector Calibration:*
  - Magnitude and phase.



$E_D$ : Directivity  
 $E_S$ : Source Match  
 $E_R$ : Frequency Tracking

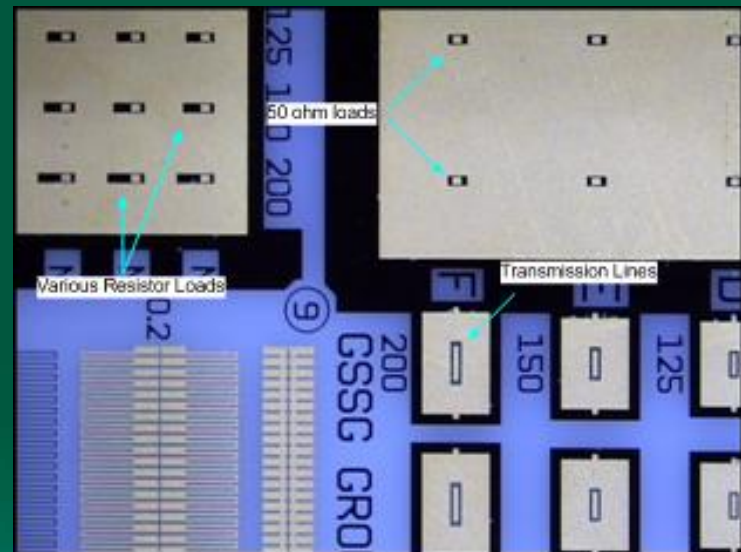
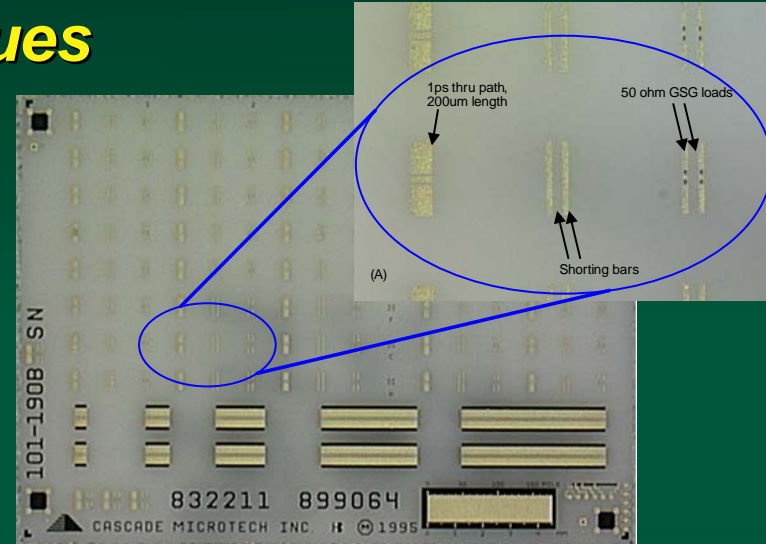
$$\Gamma_m = E_D + \frac{E_R \Gamma_a}{1 - E_S \Gamma_a}$$



# Vector RF Calibration

## 2-port techniques

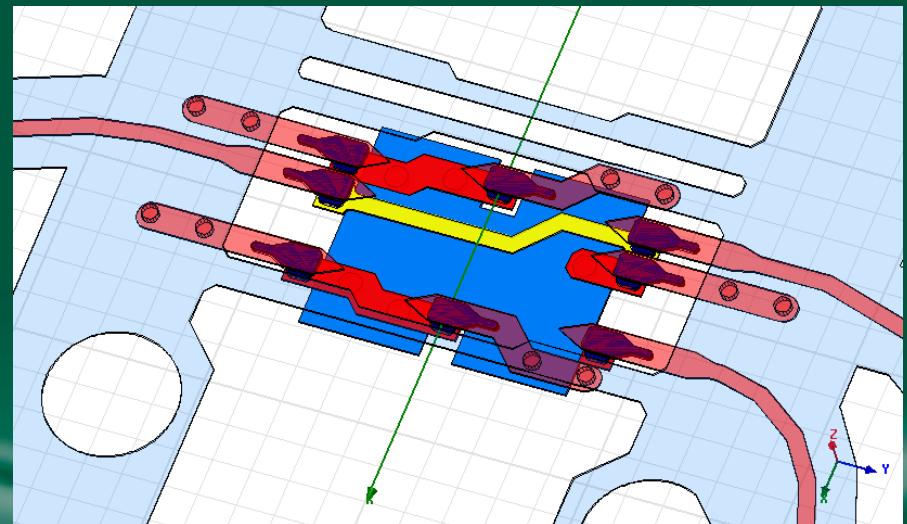
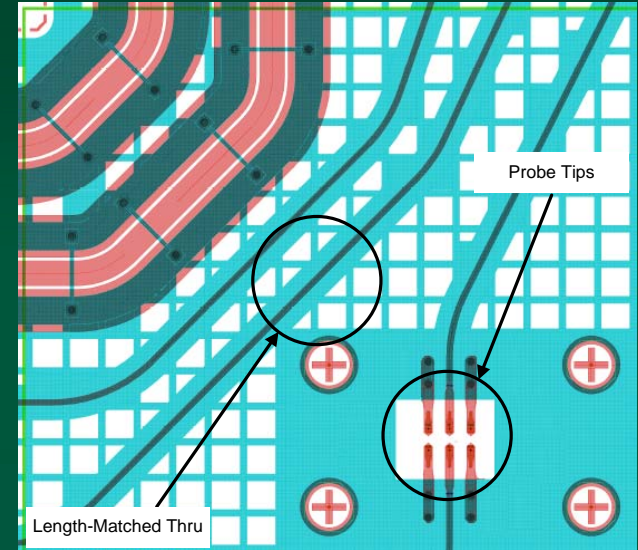
- Measure 4 standards:
  - Short
  - Open
  - Load (50 ohms)
  - Thru path between ports.
- Disadvantages:
  - Probe standards.
  - Standards must match probe topology.
  - VNA software required.
  - Difficult to integrate within an ATE environment.
  - Vector calibration usually not required for KGD test.



# Scalar RF Calibration

## *Simple characterization techniques*

- Direct Measurement:
  - Use two ports.
  - Measure the loss, end-to-end.
  - Divide loss by 2.
  
- Implementation:
  - Length-matched thru.
  - Cal-thru.
  - On-die thru.

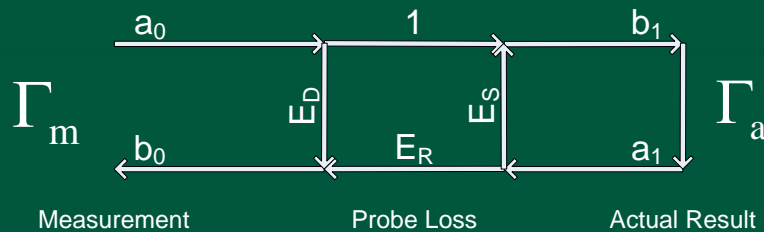




# Scalar RF Calibration

## Measure Short-Open to characterize RF path loss

- Directivity ( $E_D$ ) and Source Match ( $E_S$ ) are generally small.
- Probe Short, Open. Take average.
- *Predicted loss is usually within 0.2dB @ 2 GHz*



$$\Gamma_m = E_D + \frac{E_R \Gamma_a}{1 - E_S \Gamma_a}$$

$$\Gamma_{m-Open} \Big|_{\Gamma_a=1} = E_D + \frac{E_R}{1 - E_S};$$

$$\Gamma_{m-Short} \Big|_{\Gamma_a=-1} = E_D - \frac{E_R}{1 + E_S}$$

$$E_D \downarrow 0; E_S \downarrow 0; \quad \Gamma_m = E_R \Gamma_a$$

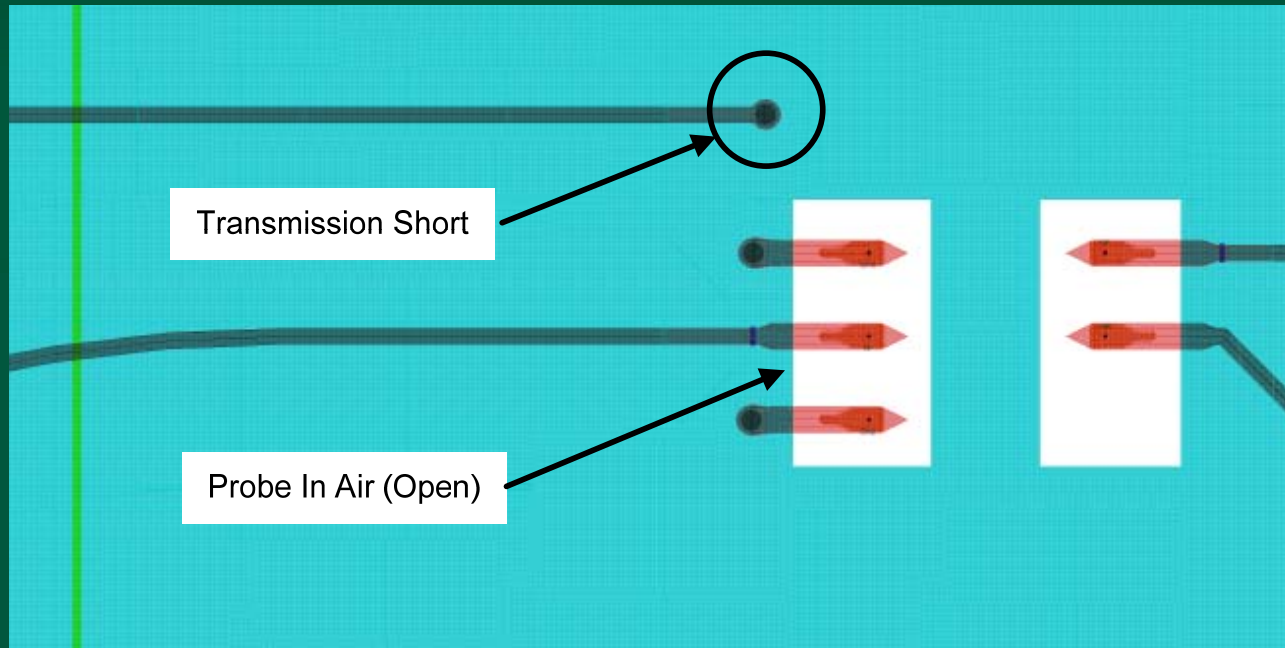
$$E_R = \frac{\Gamma_{m-Open} - \Gamma_{m-Short}}{2}$$



# Scalar RF Calibration

*Measure Short-Open to characterize RF path loss*

- Incorporate Shorting path into probe:

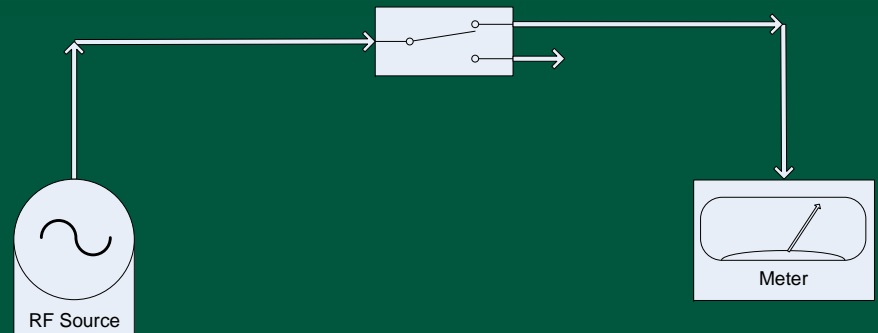


# Clearing the Obstacles

*Cater your system for Parallel test*

Time →

Insertion Loss	Isolation	Insertion Loss	Isolation
Position 1		Position 2	

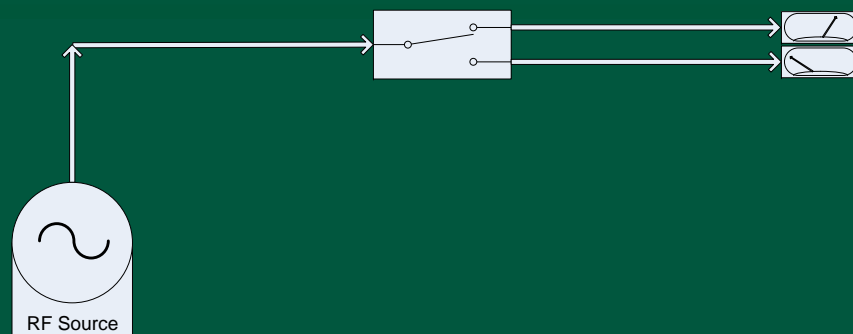


# Clearing the Obstacles

*Cater your system for Parallel test*

Time →

Insertion Loss	Isolation	Insertion Loss	Isolation
Position 1		Position 2	

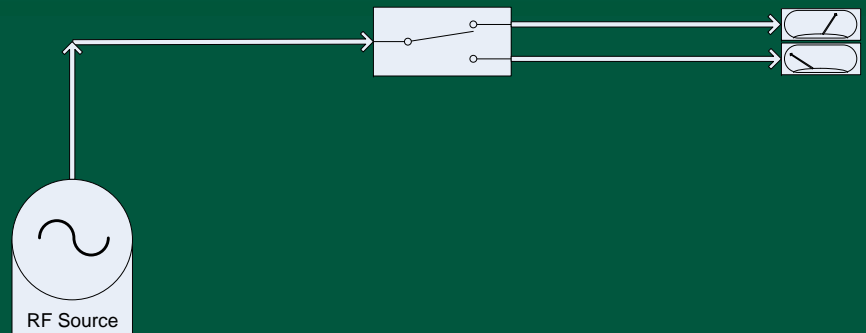


# Clearing the Obstacles

*Cater your system for Parallel test*

Time →

Insertion Loss	Isolation
Isolation	Insertion Loss
Position 1	Position 2



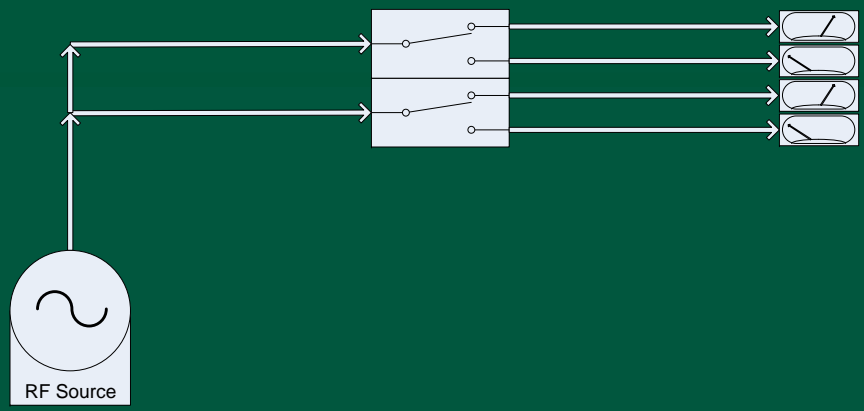
# Clearing the Obstacles

*Cater your system for Parallel test*

Time →

Insertion Loss	Isolation
Isolation	Insertion Loss
Position 1	Position 2

Insertion Loss	Isolation
Isolation	Insertion Loss
Position 1	Position 2

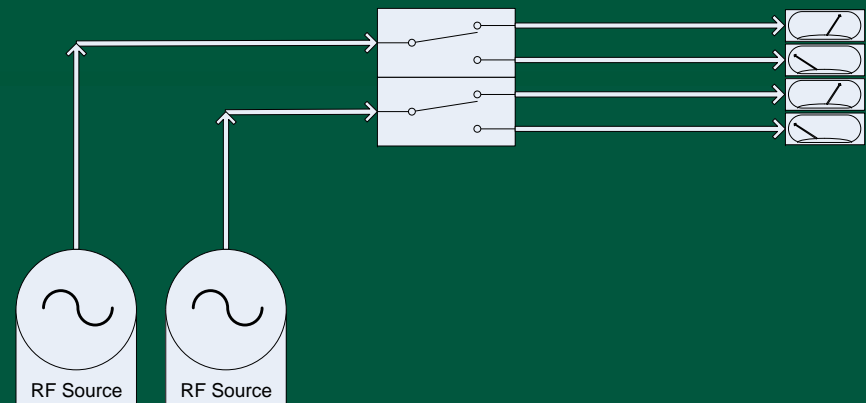


# Clearing the Obstacles

*Cater your system for Parallel test*

Time →

Insertion Loss	Isolation
Isolation	Insertion Loss
Position 1	Position 2
Insertion Loss	Isolation
Isolation	Insertion Loss
Position 1	Position 2



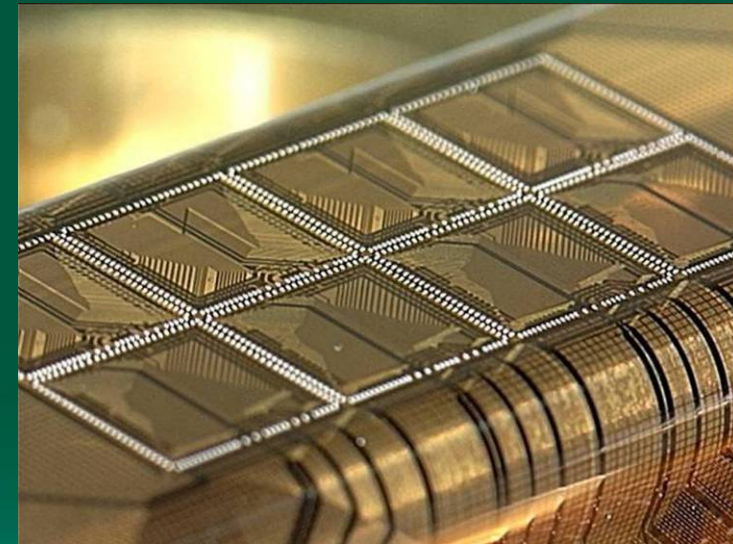
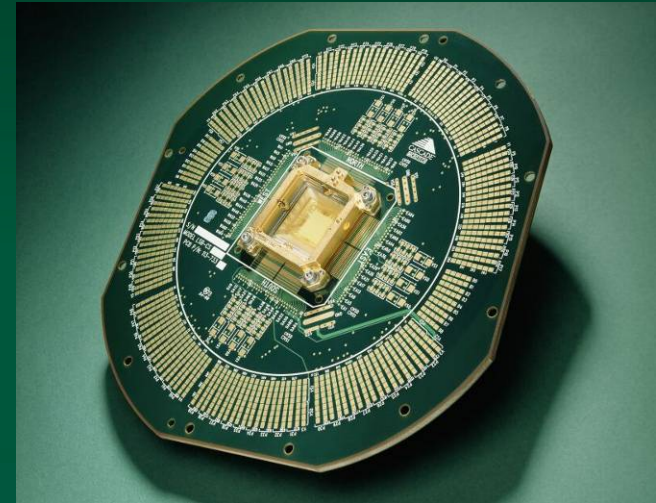
Reduce Isolation requirements  
by testing  
at different frequencies.



# Debugging the Test Program

## *A significant challenge of Parallel RF Test*

- *Reality Check:*
  - *Most devices are not as simple as this example...*
- *Parallel Test Setup:*
  - *Develop test without burning up wafers.*
  - *Develop test with few wafers at a manual station.*
  - *Optimize test time.*
  - *Assure complete test coverage of part.*



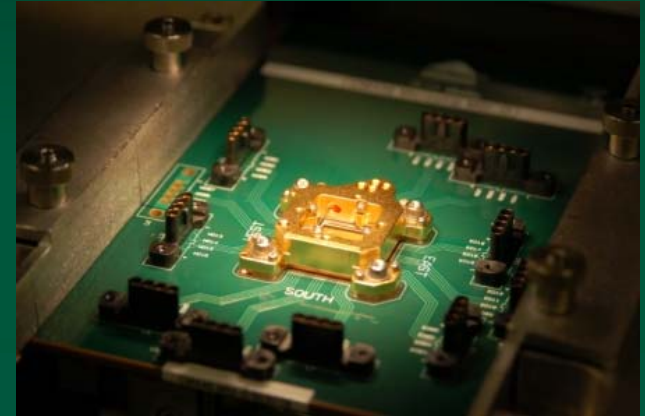


# Pyramid Accel™ Concept

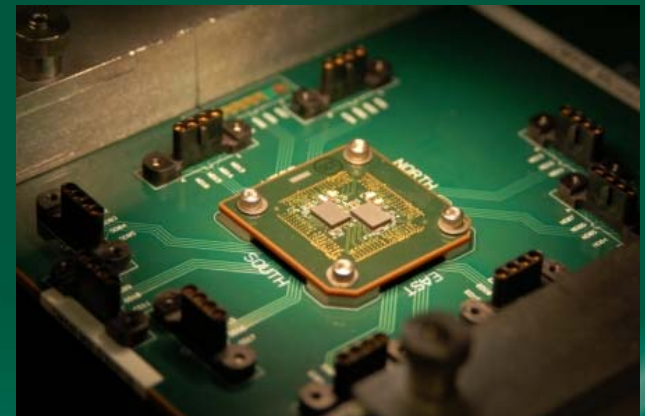
## *Enabling Parallel RF Test*

- Design Test program.
- Design Probe card.
- Obtain blind-build packaged parts.
- Temporarily eliminate:
  - Wafer prober (cost & availability)
  - Wafers (develop prior to their arrival)
- Test with packaged parts.
- Optimize test program.

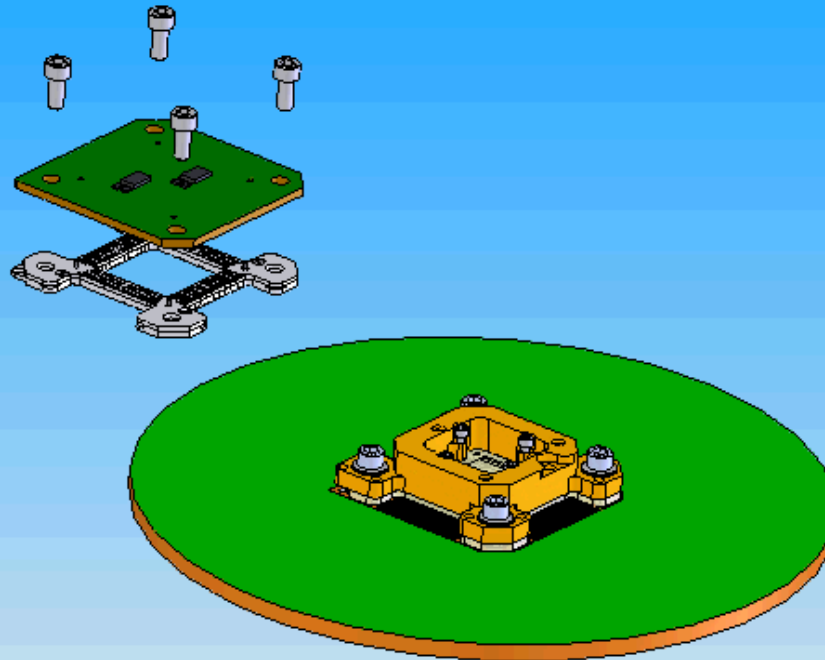
Pyramid Probe “Core”



Pyramid Accel Debug Fixture



# Pyramid Accel™ Fixture

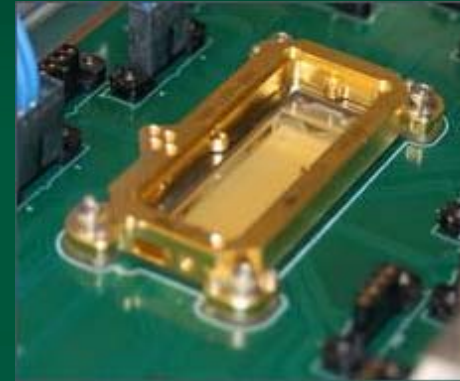


# Pyramid Accel™ Fixture

## *Enabling Parallel RF Test*

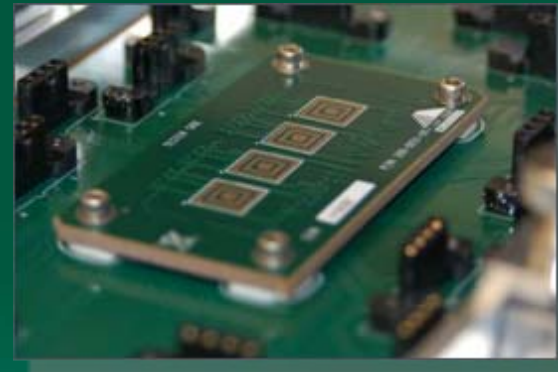
- Test features:
  - Enables test of complex probe cards.
  - Socket option allows you to replace blind-build parts.
  - Electrical performance similar to Pyramid Probe performance.

Pyramid Probe Core



- Golden Probe:
  - Keep an Accel fixture at the production test site.
  - Validate probe card & test program are still functioning properly.

Pyramid Accel Debug Fixture



# Summary

## *Parallel RF Test presents a unique Challenge*

- Calibrate RF path loss using scalar techniques.
- Characterize port-to-port isolation.
- Design probe card to optimize for parallel test.
- Write a true parallel-processing test program.
- Optimize your test program as early as possible.
  - Assure adequate test coverage.
  - Lower your test cost per die.



# Summary

Thank You!

